MA2Z785 (MA785)

Silicon epitaxial planar type

For super high speed switching

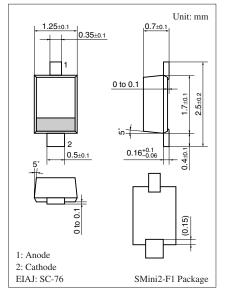
For small current rectification

Features

- High-density mounting is possible
- Forward current (Average) $I_{F(AV)} = 100$ mA rectification is possible
- Optimum for high frequency rectification because of its short reverse recovery time t_{rr}
- \bullet Low forward voltage $V_{\rm F}$ and good rectification efficiency
- Reverse voltage $V_R = 50$ V is guaranteed

5 "					
Parameter	Symbol	Rating	Unit		
Reverse voltage	V _R	50	V		
Repetitive peak reverse voltage	V _{RRM}	50	V		
Peak forward current	I _{FM}	300	mA		
Forward current (Average)	I _{F(AV)}	100	mA		
Non-repetitive peak forward surge current *	I _{FSM}	1	А		
Junction temperature	Tj	125	°C		
Storage temperature	T _{stg}	-55 to +125	°C		

Absolute Maximum Ratings $T_a = 25^{\circ}C$



Marking Symbol: 2E

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

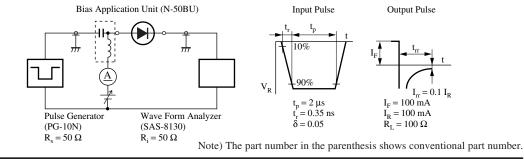
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _F	$I_F = 100 \text{ mA}$			0.55	V
Reverse current	I _R	$V_R = 50 V$			30	μΑ
Terminal capacitance	Ct	$V_R = 0 V, f = 1 MHz$		25		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$		3.0		ns
		$I_{rr} = 0.1 \ I_R, R_L = 100 \ \Omega$				

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

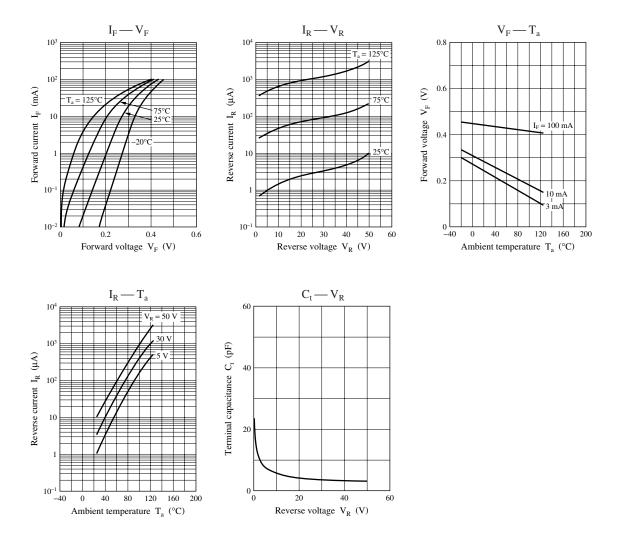
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 200 MHz.





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